

# **2012 13th IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems**

## **(IVherm 2012)**

**San Diego, California, USA  
30 May-1 June 2012**

**Pages 1-752**



**IEEE Catalog Number: CFP12ITH-PRT  
ISBN: 978-1-4244-9533-7**

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